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Understanding Embedded - FPGAs (Field Programmable Gate Array)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details	
Product Status	Active
Number of LABs/CLBs	32256
Number of Logic Elements/Cells	-
Total RAM Bits	294912
Number of I/O	586
Number of Gates	2000000
Voltage - Supply	1.425V ~ 1.575V
Mounting Type	Surface Mount
Operating Temperature	-40°C ~ 85°C (TA)
Package / Case	896-BGA
Supplier Device Package	896-FBGA (31x31)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/ax2000-1fg896i

Packaging Data

Refer to the following documents located on the Microsemi SoC Products Group website for additional packaging information.

- Package Mechanical Drawings
- Package Thermal Characteristics and Weights
- Hermatic Package Mechanical Information

Contact your local Microsemi representative for device availability.

Figure 1-2 • **Axcelerator Family Interconnect Elements**

Logic Modules

Microsemi's Axcelerator family provides two types of logic modules: the register cell (R-cell) and the combinatorial cell (C-cell). The Axcelerator device can implement more than 4,000 combinatorial functions of up to five inputs (Figure 1-3).

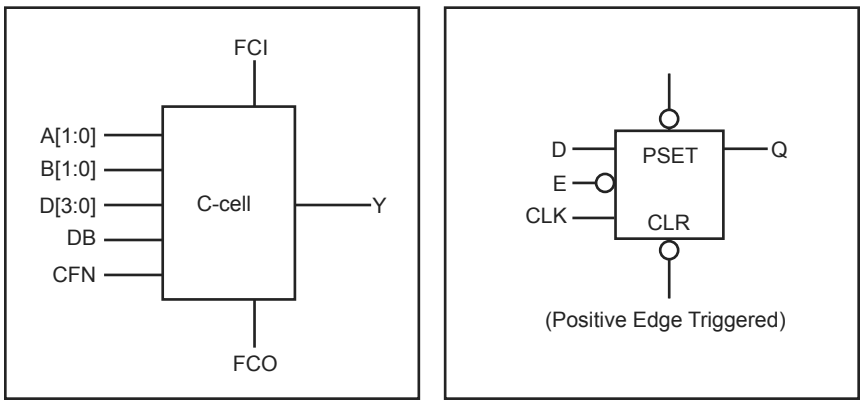


Figure 1-3 • **AX C-Cell and R-Cell**

The R-cell contains a flip-flop featuring asynchronous clear, asynchronous preset, and active-low enable control signals (Figure 1-3). The R-cell registers feature programmable clock polarity selectable on a register-by-register basis. This provides additional flexibility (e.g., easy mapping of dual-data-rate functions into the FPGA) while conserving valuable clock resources. The clock source for the R-cell can be chosen from the hardwired clocks, routed clocks, or internal logic.

User-Defined Supply Pins

VREF **Supply Voltage**

Reference voltage for I/O banks. VREF pins are configured by the user from regular I/O pins; VREF pins are not in fixed locations. There can be one or more VREF pins in an I/O bank.

Global Pins

HCLKA/B/C/D **Dedicated (Hardwired) Clocks A, B, C and D**

These pins are the clock inputs for sequential modules or north PLLs. Input levels are compatible with all supported I/O standards. There is a P/N pin pair for support of differential I/O standards. Single-ended clock I/Os can only be assigned to the P side of a paired I/O. This input is directly wired to each R-cell and offers clock speeds independent of the number of R-cells being driven. When the HCLK pins are unused, it is recommended that they are tied to ground.

CLKE/F/G/H **Routed Clocks E, F, G, and H**

These pins are clock inputs for clock distribution networks or south PLLs. Input levels are compatible with all supported I/O standards. There is a P/N pin pair for support of differential I/O standards. Single-ended clock I/Os can only be assigned to the P side of a paired I/O. The clock input is buffered prior to clocking the R-cells. When the CLK pins are unused, Microsemi recommends that they are tied to ground.

JTAG/Probe Pins

PRA/B/C/D **Probe A, B, C and D**

The Probe pins are used to output data from any user-defined design node within the device (controlled with Silicon Explorer II). These independent diagnostic pins can be used to allow real-time diagnostic output of any signal path within the device. The pins' probe capabilities can be permanently disabled to protect programmed design confidentiality. The probe pins are of LVTTL output levels.

TCK **Test Clock**

Test clock input for JTAG boundary-scan testing and diagnostic probe (Silicon Explorer II).

TDI **Test Data Input**

Serial input for JTAG boundary-scan testing and diagnostic probe. TDI is equipped with an internal 10 kΩ pull-up resistor.

TDO **Test Data Output**

Serial output for JTAG boundary-scan testing.

TMS **Test Mode Select**

The TMS pin controls the use of the IEEE 1149.1 boundary-scan pins (TCK, TDI, TDO, TRST). TMS is equipped with an internal 10 kΩ pull-up resistor.

TRST **Boundary Scan Reset Pin**

The TRST pin functions as an active-low input to asynchronously initialize or reset the boundary scan circuit. The TRST pin is equipped with a 10 kΩ pull-up resistor.

Special Functions

LP **Low Power Pin**

The LP pin controls the low power mode of Axcelerator devices. The device is placed in the low power mode by connecting the LP pin to logic high. To exit the low power mode, the LP pin must be set Low. Additionally, the LP pin must be set Low during chip powering-up or chip powering-down operations. See "Low Power Mode" on page 2-106 for more details.

NC **No Connection**

This pin is not connected to circuitry within the device. These pins can be driven to any voltage or can be left floating with no effect on the operation of the device.

I/O Standard Electrical Specifications

***Table 2-18* • Input Capacitance**

Symbol	Parameter	Conditions	Min.	Max.	Units
C_{IN}	Input Capacitance	VIN = 0, f = 1.0 MHz		10	pF
C_{INCLK}	Input Capacitance on HCLK and RCLK Pin	VIN = 0, f = 1.0 MHz		10	pF

Table 2-19* • I/O Input Rise Time and Fall Time

Input Buffer	Input Rise/Fall Time (min.)	Input Rise/Fall Time (max.)
LVTTL	No Requirement	50 ns
LVCMOS 2.5V	No Requirement	50 ns
LVCMOS 1.8V	No Requirement	50 ns
LVCMOS 1.5V	No Requirement	50 ns
PCI	No Requirement	50 ns
PCIX	No Requirement	50 ns
GTL+	No Requirement	50 ns
HSTL	No Requirement	50 ns
SSTL2	No Requirement	50 ns
HSTL3	No Requirement	50 ns
LVDS	No Requirement	50 ns
LVPECL	No Requirement	50 ns

*Note: *Input Rise/Fall time applies to all inputs, be it clock or data. Inputs have to ramp up/down linearly, in a monotonic way. Glitches or a plateau may cause double clocking. They must be avoided. For output rise/fall time, refer to the IBIS models for extraction.*

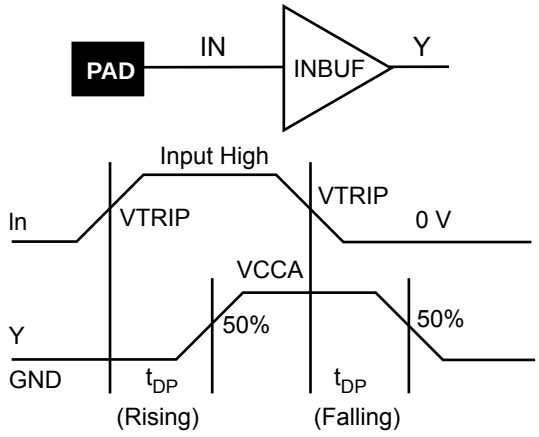


***Figure 2-9 •* Input Buffer Delays**

HSTL Class I

High-Speed Transceiver Logic is a general-purpose high-speed 1.5 V bus standard (EIA/JESD8-6). The Axcelerator devices support Class I. This requires a differential amplifier input buffer and a push-pull output buffer.

***Table 2-41* • DC Input and Output Levels**

VIL		VIH		VOL	VOH	IOL	IOH
Min., V	**Max., V**	**Min., V**	**Max., V**	**Max., V**	**Min., V**	**mA**	**mA**
-0.3	VREF – 0.1	VREF + 0.1	3.6	0.4	VCC – 0.4	8	-8

AC Loadings

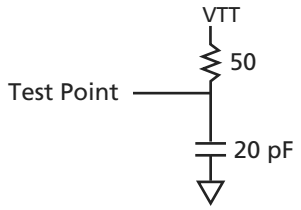


***Figure 2-20 •* AC Test Loads**

***Table 2-42* • AC Waveforms, Measuring Points, and Capacitive Loads**

Input Low (V)	Input High (V)	Measuring Point* (V)	VREF (typ) (V)	C_{load} (pF)
VREF –0.5	VREF + 0.5	VREF	0.75	20

*Note: * Measuring Point = VTRIP*

Timing Characteristics

***Table 2-43* • 1.5 V HSTL Class I I/O Module**
Worst-Case Commercial Conditions VCCA = 1.425 V, VCCI = 1.425 V, T_J = 70°C

		–2 Speed		–1 Speed		Std Speed		
Parameter	**Description**	**Min.**	**Max.**	**Min.**	**Max.**	**Min.**	**Max.**	**Units**
1.5 V HSTL Class I I/O Module Timing								
t_{DP}	Input Buffer		1.80		2.05		2.41	ns
t_{PY}	Output Buffer		4.90		5.58		6.56	ns
t_{ICLKQ}	Clock-to-Q for the I/O input register		0.67		0.77		0.90	ns
t_{OCLKQ}	Clock-to-Q for the I/O output register and the I/O enable register		0.67		0.77		0.90	ns
t_{SUD}	Data Input Set-Up		0.23		0.27		0.31	ns
t_{SUE}	Enable Input Set-Up		0.26		0.30		0.35	ns
t_{HD}	Data Input Hold		0.00		0.00		0.00	ns
t_{HE}	Enable Input Hold		0.00		0.00		0.00	ns
t_{CPWHL}	Clock Pulse Width High to Low	0.39		0.39		0.39		ns
t_{CPWLH}	Clock Pulse Width Low to High	0.39		0.39		0.39		ns
t_{WASYN}	Asynchronous Pulse Width	0.37		0.37		0.37		ns
t_{REASYN}	Asynchronous Recovery Time		0.13		0.15		0.17	ns
t_{HASYN}	Asynchronous Removal Time		0.00		0.00		0.00	ns
t_{CLR}	Asynchronous Clear-to-Q		0.23		0.27		0.31	ns
t_{PRESET}	Asynchronous Preset-to-Q		0.23		0.27		0.31	ns

PLL Configurations

The following rules apply to the different PLL inputs and outputs:

Reference Clock

The RefCLK can be driven by (Figure 2-50):

1. Global routed clocks (CLKE/F/G/H) or user-created clock network
2. CLK1 output of an adjacent PLL
3. [H]CLKxP (single-ended or voltage-referenced)
4. [H]CLKxP/[H]CLKxN pair (differential modes like LVPECL or LVDS)

Feedback Clock

The feedback clock can be driven by (Figure 2-51 on page 2-78):

1. Global routed clocks (CLKE/F/G/H) or user-created clock network
2. External [H]CLKxP/N I/O pad(s) from the adjacent PLL cell
3. An internal signal from the PLL block

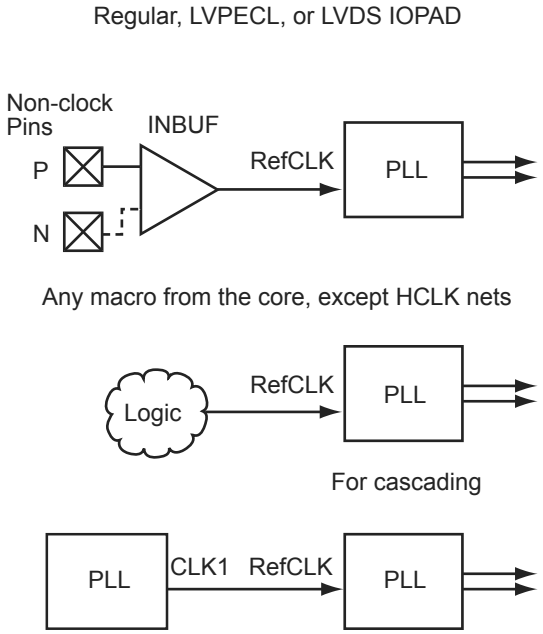


Figure 2-50 • **Reference Clock Connections**

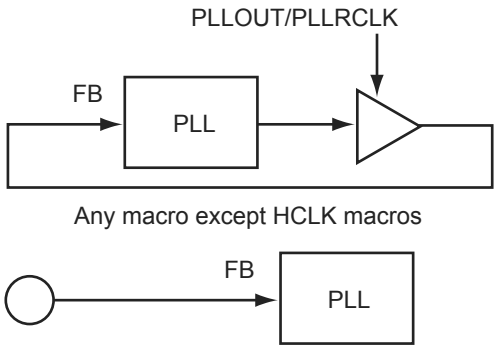


Figure 2-51 • **Feedback Clock Connections**

***Table 2-90* • Two RAM Blocks Cascaded**
Worst-Case Commercial Conditions VCCA = 1.425 V, VCCI = 3.0 V, T_J = 70°C

		–2 Speed		–1 Speed		Std Speed		
Parameter	**Description**	**Min.**	**Max.**	**Min.**	**Max.**	**Min.**	**Max.**	**Units**
Write Mode								
t_{WDASU}	Write Data Setup vs. WCLK		1.39		1.59		1.87	ns
t_{WDAHD}	Write Data Hold vs. WCLK		0.00		0.00		0.00	ns
t_{WADSU}	Write Address Setup vs. WCLK		1.39		1.59		1.87	ns
t_{WADHD}	Write Address Hold vs. WCLK		0.00		0.00		0.00	ns
t_{WENSU}	Write Enable Setup vs. WCLK		1.39		1.59		1.87	ns
t_{WENHD}	Write Enable Hold vs. WCLK		0.00		0.00		0.00	ns
t_{WCKH}	WCLK Minimum High Pulse Width	0.75		0.75		0.75		ns
t_{WCLK}	WCLK Minimum Low Pulse Width	1.76		1.76		1.76		ns
t_{WCKP}	WCLK Minimum Period	2.51		2.51		2.51		ns
Read Mode								
t_{RADSU}	Read Address Setup vs. RCLK		1.71		1.94		2.28	ns
t_{RADHD}	Read Address Hold vs. RCLK		0.00		0.00		0.00	ns
t_{RENSU}	Read Enable Setup vs. RCLK		1.71		1.94		2.28	ns
t_{RENHD}	Read Enable Hold vs. RCLK		0.00		0.00		0.00	ns
$t_{RCK2RD1}$	RCLK-To-OUT (Pipelined)		1.43		1.63		1.92	ns
$t_{RCK2RD2}$	RCLK-To-OUT (Non-Pipelined)		2.26		2.58		3.03	ns
t_{RCLKH}	RCLK Minimum High Pulse Width	0.73		0.73		0.73		ns
t_{RCLKL}	RCLK Minimum Low Pulse Width	1.89		1.89		1.89		ns
t_{RCKP}	RCLK Minimum Period	2.62		2.62		2.62		ns

Note: Timing data for these two cascaded RAM blocks uses a depth of 8,192. For all other combinations, use Microsemi's timing software.

Glitch Elimination

An analog filter is added to each FIFO controller to guarantee glitch-free FIFO-flag logic.

Overflow and Underflow Control

The counter MSB keeps track of the difference between the read address (RA) and the write address (WA). The EMPTY flag is set when the read and write addresses are equal. To prevent underflow, the write address is double-sampled by the read clock prior to comparison with the read address (part A in Figure 2-64). To prevent overflow, the read address is double-sampled by the write clock prior to comparison to the write address (part B in Figure 2-64).

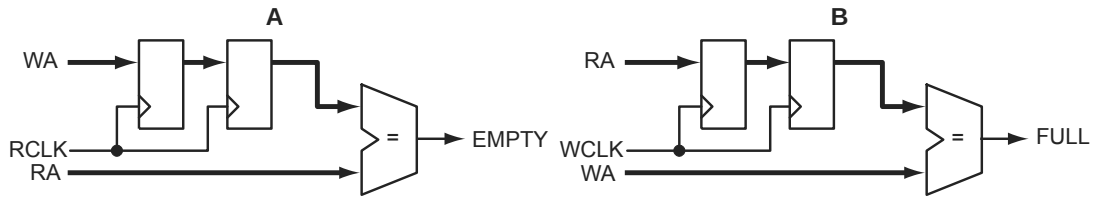


Figure 2-64 • **Overflow and Underflow Control**

FIFO Configurations

Unlike the RAM, the FIFO's write width and read width cannot be specified independently. For the FIFO, the write and read widths must be the same. The WIDTH pins are used to specify one of six allowable word widths, as shown in Table 2-96.

Table 2-96 • **FIFO Width Configurations**

WIDTH(2:0)	W x D
000	1 x 4k
001	2 x 2k
010	4 x 1k
011	9 x 512
100	18 x 256
101	36 x 128
11x	reserved

The DEPTH pins allow RAM cells to be cascaded to create larger FIFOs. The four pins allow depths of 2, 4, 8, and 16 to be specified. Table 2-86 on page 2-87 describes the FIFO depth options for various data width and memory blocks.

Interface

Figure 2-65 on page 2-99 shows a logic block diagram of the Axcelerator FIFO module.

Cascading FIFO Blocks

FIFO blocks can be cascaded to create deeper FIFO functions. When building larger FIFO blocks, if the word width can be fractured in a multi-bit FIFO, the fractured word configuration is recommended over a cascaded configuration. For example, 256x36 can be configured as two blocks of 256x18. This should be taken into account when building the FIFO blocks manually. However, when using SmartGen, the user only needs to specify the depth and width of the necessary FIFO blocks. SmartGen automatically configures these blocks to optimize performance.

***Table 2-99* • Two FIFO Blocks Cascaded**
Worst-Case Commercial Conditions VCCA = 1.425 V, VCCI = 3.0 V, T_J = 70°C

		–2 Speed		–1 Speed		Std Speed		
Parameter	**Description**	**Min.**	**Max.**	**Min.**	**Max.**	**Min.**	**Max.**	**Units**
FIFO Module Timing								
t_{WSU}	Write Setup		13.75		15.66		18.41	ns
t_{WHD}	Write Hold		0.00		0.00		0.00	ns
t_{WCKH}	WCLK High		0.75		0.75		0.75	ns
t_{WCKL}	WCLK Low		1.76		1.76		1.76	ns
t_{WCKP}	Minimum WCLK Period	2.51		2.51		2.51		ns
t_{RSU}	Read Setup		14.33		16.32		19.19	ns
t_{RHD}	Read Hold		0.00		0.00		0.00	ns
t_{RCKH}	RCLK High		0.73		0.73		0.73	ns
t_{RCKL}	RCLK Low		1.89		1.89		1.89	ns
t_{RCKP}	Minimum RCLK period	2.62		2.62		2.62		ns
t_{CLRHF}	Clear High		0.00		0.00		0.00	ns
t_{CLR2FF}	Clear-to-flag (EMPTY/FULL)		1.92		2.18		2.57	ns
t_{CLR2AF}	Clear-to-flag (AEMPTY/AFULL)		4.39		5.00		5.88	ns
t_{CK2FF}	Clock-to-flag (EMPTY/FULL)		2.13		2.42		2.85	ns
t_{CK2AF}	Clock-to-flag (AEMPTY/AFULL)		5.04		5.75		6.75	ns
$t_{RCK2RD1}$	RCLK-To-OUT (Pipelined)		1.43		1.63		1.92	ns
$t_{RCK2RD2}$	RCLK-To-OUT (Nonpipelined)		2.26		2.58		3.03	ns

Note: Timing data for these two cascaded FIFO blocks uses a depth of 8,192. For all other combinations, use Microsemi's timing software.

TDO

TDO is normally tristated, and it is active only when the TAP controller is in the "Shift_DR" state or "Shift_IR" state. The least significant bit of the selected register (i.e. IR or DR) is clocked out to TDO first by the falling edge of TCK.

TAP Controller

The TAP Controller is compliant with the IEEE Standard 1149.1. It is a state machine of 16 states that controls the Instruction Register (IR) and the Data Registers (such as BSR, IDCODE, USRCODE, BYPASS, etc.). The TAP Controller steps into one of the states depending on the sequence of TMS at the rising edges of TCK.

Instruction Register (IR)

The IR has five bits (IR4 to IR0). At the TRST state, IR is reset to IDCODE. Each time when IR is selected, it goes through "select IR-Scan," "Capture-IR," "Shift-IR," all the way through "Update-IR." When there is no test error, the first five data bits coming out of TDO during the "Shift-IR" will be "10111". If a test error occurs, the last three bits will contain one to three zeroes corresponding to negatively asserted signals: "TDO_ERRORB," "PROBA_ERRORB," and "PROBB_ERRORB." The error(s) will be erased when the TAP is at the "Update-IR" or the TRST state. When in user mode start-up sequence, if the micro-probe has not been used, the "PROBA_ERRORB" is used as a "Power-up done successfully" flag.

Data Registers (DRs)

Data registers are distributed throughout the chip. They store testing/programming vectors. The MSB of a data register is connected to TDI, while the LSB is connected to TDO. There are different types of data registers. Descriptions of the main registers are as follow:

1. IDCODE:

   The IDCODE is a 20-bit hard coded JTAG Silicon Signature. It is a hardwired device ID code, which contains the Microsemi identity, part number, and version number in a specific JTAG format.

2. USERCODE:

   The USERCODE is a 33-bit programmable register. However, only 20 bits are allocated to use as JTAG Silicon Signature. It is a supplementary identity code for the user to program information to distinguish different programmed parts. USERCODE fuses will read out as "zeroes" when not programmed, so only the "1" bits need to be programmed.

3. Boundary-Scan Register (BSR):

   Each I/O contains three Boundary-Scan Cells. Each cell has a shift register bit, a latch, and two MUXes. The boundary-scan cells are used for the Output-enable (E), Output (O), and Input (I) registers. The bit order of the boundary-scan cells for each of them is E-O-I. The boundary-scan cells are then chained serially to form the Boundary-Scan Register (BSR). The length of the BSR is the number of I/Os in the die multiplied by three.

4. Bypass Register (BYR):

   This is the "1-bit" register. It is used to shorten the TDI-TDO serial chain in board-level testing to only one bit per device not being tested. It is also selected for all "reserved" or unused instructions.

Probing

Internal activities of the JTAG interface can be observed via the Silicon Explorer II probes: "PRA," "PRB," "PRC," and "PRD."

Special Fuses

Security

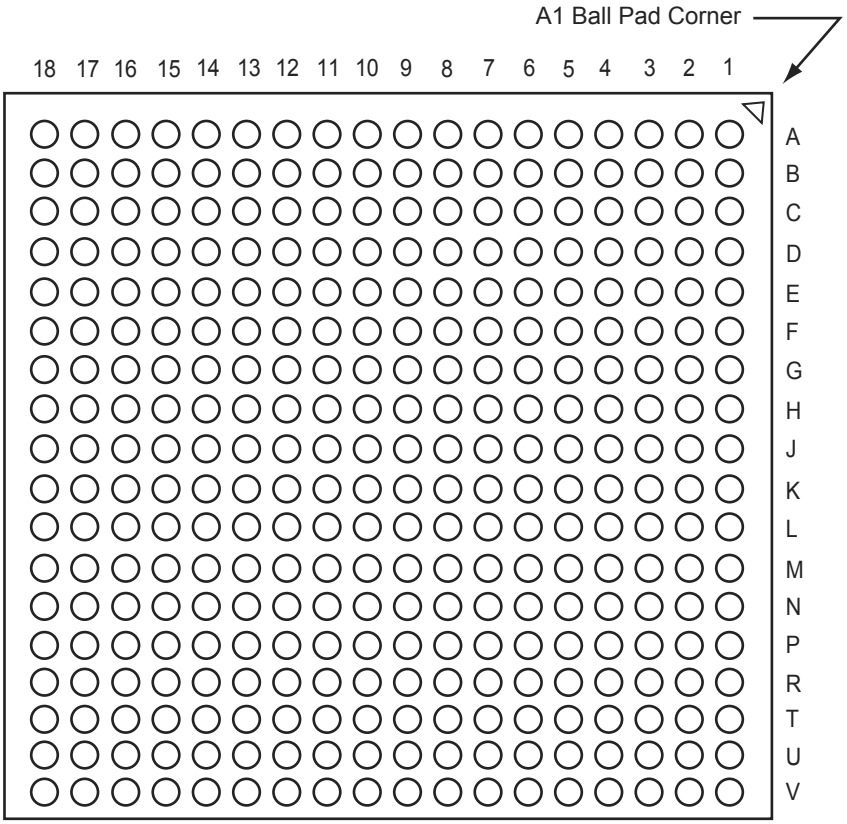
Microsemi antifuse FPGAs, with FuseLock technology, offer the highest level of design security available in a programmable logic device. Since antifuse FPGAs are live-at power-up, there is no bitstream that can be intercepted, and no bitstream or programming data is ever downloaded to the device during power-up, thus protecting against device cloning. In addition, special security fuses are hidden

BG729	
AX1000 Function	Pin Number
IO54PB1F5	E20
IO55NB1F5	E21
IO55PB1F5	D21
IO56NB1F5	H19
IO56PB1F5	G19
IO57NB1F5	D22
IO57PB1F5	C22
IO58NB1F5	B23
IO58PB1F5	A23
IO59NB1F5	D23
IO59PB1F5	C23
IO60NB1F5	G21
IO60PB1F5	G20
IO61NB1F5	E23
IO61PB1F5	E22
IO62NB1F5	F22
IO62PB1F5	F21
IO63NB1F5	H20
IO63PB1F5	J19
Bank 2	
IO64NB2F6	J21
IO64PB2F6	H21
IO65NB2F6	F24
IO65PB2F6	F23
IO66NB2F6	F26
IO66PB2F6	F25
IO67NB2F6	E26
IO67PB2F6	E25
IO68NB2F6	J22
IO68PB2F6	H22
IO69NB2F6	G24
IO69PB2F6	G23
IO70NB2F6	K20
IO70PB2F6	J20
IO71NB2F6	G26
IO71PB2F6	G25
IO72NB2F6	J24

BG729	
AX1000 Function	Pin Number
IO72PB2F6	J23
IO73NB2F6	H24
IO73PB2F6	H23
IO74NB2F7	L21
IO74PB2F7	K21
IO75NB2F7	G27
IO75PB2F7	F27
IO76NB2F7	K23
IO76PB2F7	K22
IO77NB2F7	H26
IO77PB2F7	H25
IO78NB2F7	K25
IO78PB2F7	K24
IO79NB2F7	J26
IO79PB2F7	J25
IO80NB2F7	M20
IO80PB2F7	L20
IO81NB2F7	J27
IO81PB2F7	H27
IO82NB2F7	L23
IO82PB2F7	L22
IO83NB2F7	L25
IO83PB2F7	L24
IO84NB2F7	N21
IO84PB2F7	M21
IO85NB2F8	K27
IO85PB2F8	K26
IO86NB2F8	M23
IO86PB2F8	M22
IO87NB2F8	M25
IO87PB2F8	M24
IO88NB2F8	L27
IO88PB2F8	L26
IO89NB2F8	M27
IO89PB2F8	M26
IO90NB2F8	N23
IO90PB2F8	N22

BG729	
AX1000 Function	Pin Number
IO91NB2F8	N25
IO91PB2F8	N24
IO92NB2F8	N27
IO92PB2F8	N26
IO93NB2F8	P26
IO93PB2F8	P27
IO94NB2F8	N19
IO94PB2F8	N20
IO95NB2F8	P23
IO95PB2F8	P22
Bank 3	
IO96NB3F9	P25
IO96PB3F9	P24
IO97NB3F9	R26
IO97PB3F9	R27
IO98NB3F9	P21
IO98PB3F9	P20
IO99NB3F9	R24
IO99PB3F9	R25
IO100NB3F9	T26
IO100PB3F9	T27
IO101NB3F9	T24
IO101PB3F9	T25
IO102NB3F9	R20
IO102PB3F9	R21
IO103NB3F9	R23
IO103PB3F9	R22
IO104NB3F9	U26
IO104PB3F9	U27
IO105NB3F9	U24
IO105PB3F9	U25
IO106NB3F9	R19
IO106PB3F9	P19
IO107NB3F10	V26
IO107PB3F10	V27
IO108NB3F10	T23
IO108PB3F10	T22

FG324



Note

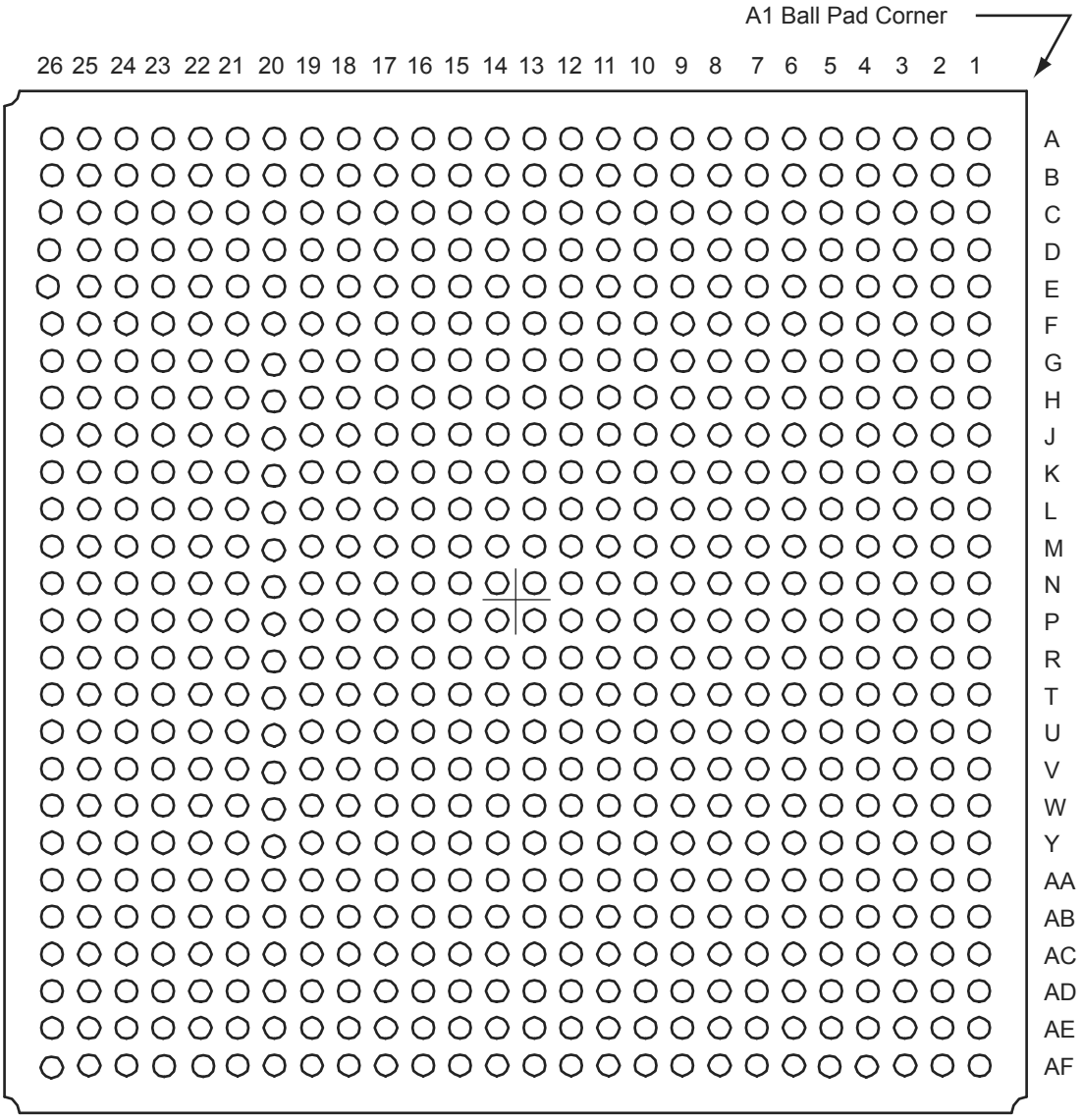
For Package Manufacturing and Environmental information, visit Resource center at http://www.microsemi.com/soc/products/rescenter/package/index.html.

FG324	
AX125 Function	**Pin Number**
IO50NB4F4/CLKFN	U9
IO50PB4F4/CLKFP	U10
Bank 5	
IO51NB5F5/CLKGN	R8
IO51PB5F5/CLKGP	R9
IO52NB5F5/CLKHN	T7
IO52PB5F5/CLKHP	T8
IO53NB5F5	U6
IO53PB5F5	U7
IO54NB5F5	V8
IO54PB5F5	V9
IO55NB5F5	V6
IO55PB5F5	V7
IO56NB5F5	U4
IO56PB5F5	U5
IO57NB5F5	T4
IO57PB5F5	T5
IO58NB5F5	V4
IO58PB5F5	V5
IO59NB5F5	V2
IO59PB5F5	V3
Bank 6	
IO60NB6F6	P5
IO60PB6F6	P6
IO61NB6F6	T2
IO61PB6F6	U3
IO62NB6F6	T1
IO62PB6F6	U1
IO63NB6F6	P1
IO63PB6F6	R1
IO64NB6F6	R3
IO64PB6F6	P3
IO65NB6F6	P2
IO65PB6F6	R2
IO66NB6F6	M3

FG324	
AX125 Function	**Pin Number**
IO66PB6F6	N3
IO67NB6F6	M2
IO67PB6F6	N2
IO68NB6F6	M1
IO68PB6F6	N1
IO69NB6F6	K4
IO69PB6F6	L4
IO70NB6F6	K1
IO70PB6F6	L1
IO71NB6F6	K3
IO71PB6F6	L3
Bank 7	
IO72NB7F7	H4
IO72PB7F7	J4
IO73NB7F7	K2
IO73PB7F7	L2
IO74NB7F7	H2
IO74PB7F7	H1
IO75NB7F7	H3
IO75PB7F7	J3
IO76NB7F7	F2
IO76PB7F7	G2
IO77NB7F7	F1
IO77PB7F7	G1
IO78NB7F7	D2
IO78PB7F7	E2
IO79NB7F7	F3
IO79PB7F7	G3
IO80NB7F7	E3
IO80PB7F7	E4
IO81NB7F7	D1
IO81PB7F7	E1
IO82NB7F7	D3
IO82PB7F7	C2
IO83NB7F7	B1

FG324	
AX125 Function	**Pin Number**
IO83PB7F7	C1
Dedicated I/O	
VCCDA	F5
GND	A1
GND	A18
GND	B17
GND	B2
GND	C16
GND	C3
GND	E16
GND	F13
GND	F6
GND	G12
GND	G7
GND	H10
GND	H11
GND	H8
GND	H9
GND	J10
GND	J11
GND	J8
GND	J9
GND	K10
GND	K11
GND	K8
GND	K9
GND	L10
GND	L11
GND	L8
GND	L9
GND	M12
GND	M7
GND	N13
GND	N6
GND	R14

FG676



Note

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FG896	
AX1000 Function	Pin Number
IO155NB4F14	AC17
IO155PB4F14	AB17
IO156NB4F14	AK19
IO156PB4F14	AJ19
IO157NB4F14	AE17
IO157PB4F14	AD17
IO158NB4F14	AJ17
IO158PB4F14	AJ18
IO159NB4F14/CLKEN	AG18
IO159PB4F14/CLKEP	AH18
IO160NB4F14/CLKFN	AG16
IO160PB4F14/CLKFP	AG17
Bank 5	
IO161NB5F15/CLKGN	AG14
IO161PB5F15/CLKGP	AG15
IO162NB5F15/CLKHN	AG13
IO162PB5F15/CLKHP	AH13
IO163NB5F15	AE14
IO163PB5F15	AD14
IO164NB5F15	AJ12
IO164PB5F15	AJ13
IO165NB5F15	AB14
IO165PB5F15	AC15
IO166NB5F15	AK11
IO166PB5F15	AK12
IO167NB5F15	AB13
IO167PB5F15	AC14
IO168NB5F15	AH11
IO168PB5F15	AH12
IO169NB5F15	AD13
IO169PB5F15	AC13
IO170NB5F15	AJ10
IO170PB5F15	AJ11
IO171NB5F16	AG11
IO171PB5F16	AG12

FG896	
AX1000 Function	Pin Number
IO172NB5F16	AK9
IO172PB5F16	AK10
IO173NB5F16	AE12
IO173PB5F16	AE13
IO174NB5F16	AG9
IO174PB5F16	AG10
IO175NB5F16	AE11
IO175PB5F16	AF11
IO176NB5F16	AH8
IO176PB5F16	AH9
IO177NB5F16	AC12
IO177PB5F16	AD12
IO178NB5F16	AJ7
IO178PB5F16	AJ8
IO179NB5F16	AF9
IO179PB5F16	AF10
IO180NB5F16	AE9
IO180PB5F16	AE10
IO181NB5F17	AC11
IO181PB5F17	AD11
IO182NB5F17	AK6
IO182PB5F17	AK7
IO183NB5F17	AF8
IO183PB5F17	AG8
IO184NB5F17	AG7
IO184PB5F17	AH7
IO185NB5F17	AC10
IO185PB5F17	AD10
IO186NB5F17	AJ5
IO186PB5F17	AJ6
IO187NB5F17	AE7
IO187PB5F17	AE8
IO188NB5F17	AF6
IO188PB5F17	AF7
IO189NB5F17	AD8

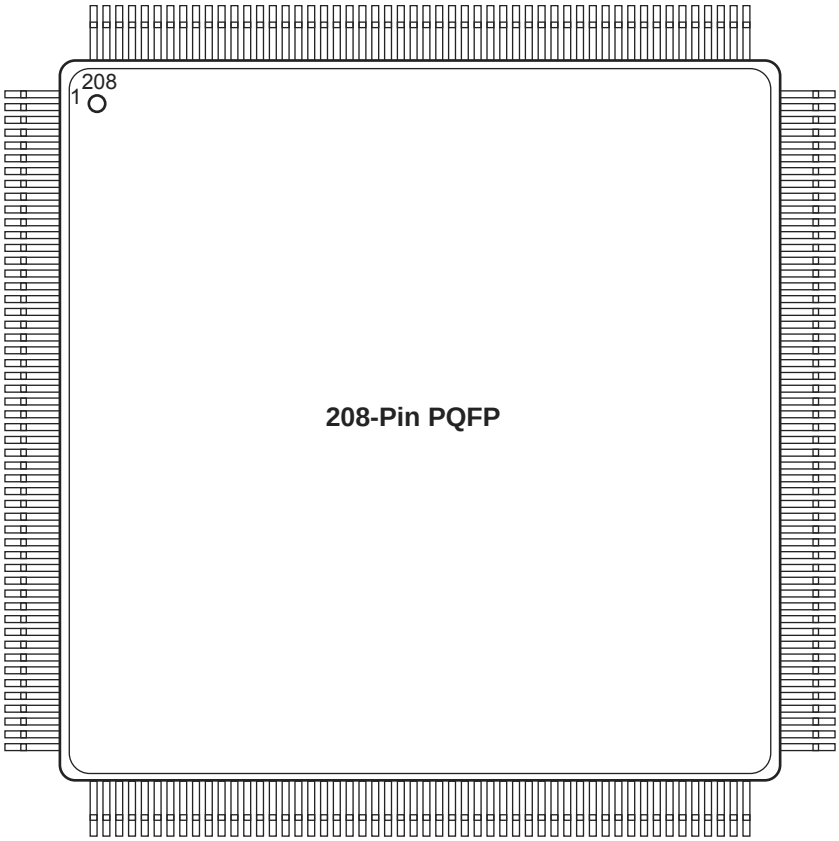
FG896	
AX1000 Function	Pin Number
IO189PB5F17	AD9
IO190NB5F17	AH6
IO190PB5F17	AG6
IO191NB5F17	AG5
IO191PB5F17	AH5
IO192NB5F17	AC8
IO192PB5F17	AC9
Bank 6	
IO193NB6F18	AB7
IO193PB6F18	AC7
IO194NB6F18	AD5
IO194PB6F18	AE5
IO195NB6F18	AB6
IO195PB6F18	AC6
IO196NB6F18	AE4
IO196PB6F18	AF4
IO197NB6F18	AA8
IO197PB6F18	AB8
IO198NB6F18	AF3
IO198PB6F18	AG3
IO199NB6F18	AC4
IO199PB6F18	AD4
IO200NB6F18	AB5
IO200PB6F18	AC5
IO201NB6F18	Y7
IO201PB6F18	AA7
IO202NB6F18	AD3
IO202PB6F18	AE3
IO203NB6F19	Y6
IO203PB6F19	AA6
IO204NB6F19	Y5
IO204PB6F19	AA5
IO205NB6F19	W8
IO205PB6F19	Y8
IO206NB6F19	AA4

FG1152	
AX2000 Function	Pin Number
Bank 0	
IO00NB0F0	D6
IO00PB0F0	C6
IO01NB0F0	H10
IO01PB0F0	H9
IO02NB0F0	F8
IO02PB0F0	G8
IO03NB0F0	A6
IO03PB0F0	B6
IO04NB0F0	C7
IO04PB0F0	D7
IO05NB0F0	K10
IO05PB0F0	J10
IO06NB0F0	F9
IO06PB0F0	G9
IO07NB0F0	F10
IO07PB0F0	G10
IO08NB0F0	E9
IO08PB0F0	E8
IO09NB0F0	J11
IO09PB0F0	K11
IO10NB0F0	C8
IO10PB0F0	D8
IO11NB0F0	K12
IO11PB0F0	J12
IO12NB0F1	G11
IO12PB0F1	H11
IO13NB0F1	G12
IO13PB0F1	H12
IO14NB0F1	A7
IO14PB0F1	B7
IO15NB0F1	H13
IO15PB0F1	J13
IO16NB0F1	C9
IO16PB0F1	D9

FG1152	
AX2000 Function	Pin Number
IO17NB0F1	F12
IO17PB0F1	F11
IO18NB0F1	E11
IO18PB0F1	E10
IO19NB0F1	F13
IO19PB0F1	G13
IO20NB0F1	A10
IO20PB0F1	A9
IO21NB0F1	K14
IO21PB0F1	K13
IO22NB0F2	B11
IO22PB0F2	B10
IO23NB0F2	C12
IO23PB0F2	C11
IO24NB0F2	A12
IO24PB0F2	A11
IO25NB0F2	H14
IO25PB0F2	J14
IO26NB0F2	D13
IO26PB0F2	D12
IO27NB0F2	F14
IO27PB0F2	G14
IO28NB0F2	E14
IO28PB0F2	E13
IO29NB0F2	B13
IO29PB0F2	B12
IO30NB0F2	C14
IO30PB0F2	C13
IO31NB0F2	H15
IO31PB0F2	J15
IO32NB0F2	A14
IO32PB0F2	B14
IO33NB0F2	K15
IO33PB0F2	L15
IO34NB0F3	D15

FG1152	
AX2000 Function	Pin Number
IO34PB0F3	D14
IO35NB0F3	A15
IO35PB0F3	B15
IO36NB0F3	B16
IO36PB0F3	A16
IO37NB0F3	G16
IO37PB0F3	G15
IO38NB0F3	D16
IO38PB0F3	C16
IO39NB0F3	K16
IO39PB0F3	L16
IO40NB0F3	D17
IO40PB0F3	C17
IO41NB0F3/HCLKAN	E16
IO41PB0F3/HCLKAP	F16
IO42NB0F3/HCLKBN	G17
IO42PB0F3/HCLKBP	F17
Bank 1	
IO43NB1F4/HCLKCN	G19
IO43PB1F4/HCLKCP	G18
IO44NB1F4/HCLKDN	E19
IO44PB1F4/HCLKDP	F19
IO45NB1F4	C18
IO45PB1F4	D18
IO46NB1F4	A18
IO46PB1F4	B18
IO47NB1F4	K19
IO47PB1F4	L19
IO48NB1F4	C19
IO48PB1F4	D19
IO49NB1F4	K20
IO49PB1F4	L20
IO50NB1F4	A19
IO50PB1F4	B19
IO51NB1F4	H20

PQ208



Note

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CQ352	
AX500 Function	Pin Number
GND	21
GND	27
GND	33
GND	39
GND	45
GND	51
GND	57
GND	63
GND	69
GND	75
GND	81
GND	88
GND	89
GND	97
GND	103
GND	109
GND	115
GND	121
GND	133
GND	145
GND	151
GND	157
GND	163
GND	169
GND	176
GND	177
GND	186
GND	192
GND	198
GND	204
GND	210
GND	216
GND	222
GND	228
GND	234

CQ352	
AX500 Function	Pin Number
GND	240
GND	246
GND	252
GND	258
GND	264
GND	265
GND	274
GND	280
GND	286
GND	292
GND	298
GND	310
GND	322
GND	330
GND	334
GND	340
GND	345
GND/LP	352
NC	91
NC	117
NC	130
NC	131
NC	148
NC	174
NC	268
NC	294
NC	307
NC	308
NC	327
NC	328
PRA	312
PRB	311
PRC	135
PRD	134
TCK	349

CQ352	
AX500 Function	Pin Number
TDI	348
TDO	347
TMS	350
TRST	351
VCCA	3
VCCA	14
VCCA	32
VCCA	56
VCCA	74
VCCA	87
VCCA	102
VCCA	114
VCCA	150
VCCA	162
VCCA	175
VCCA	191
VCCA	209
VCCA	233
VCCA	251
VCCA	263
VCCA	279
VCCA	291
VCCA	329
VCCA	339
VCCDA	2
VCCDA	44
VCCDA	90
VCCDA	116
VCCDA	132
VCCDA	149
VCCDA	178
VCCDA	221
VCCDA	266
VCCDA	293
VCCDA	309

CQ352	
AX1000 Function	Pin Number
IO131PB4F12	171
IO132NB4F12	166
IO132PB4F12	167
IO133NB4F12	164
IO133PB4F12	165
IO134NB4F12	160
IO134PB4F12	161
IO136NB4F12	158
IO136PB4F12	159
IO137NB4F12	154
IO137PB4F12	155
IO138NB4F12	152
IO138PB4F12	153
IO153NB4F14	146
IO153PB4F14	147
IO159NB4F14/CLKEN	142
IO159PB4F14/CLKEP	143
IO160NB4F14/CLKFN	136
IO160PB4F14/CLKFP	137
Bank 5	
IO161NB5F15/CLKGN	128
IO161PB5F15/CLKGP	129
IO162NB5F15/CLKHN	122
IO162PB5F15/CLKHP	123
IO167NB5F15	118
IO167PB5F15	119
IO183NB5F17	110
IO183PB5F17	111
IO184NB5F17	112
IO184PB5F17	113
IO185NB5F17	104
IO185PB5F17	105
IO186NB5F17	106
IO186PB5F17	107
IO187NB5F17	98

CQ352	
AX1000 Function	Pin Number
IO187PB5F17	99
IO188NB5F17	100
IO188PB5F17	101
IO190NB5F17	94
IO190PB5F17	95
IO192NB5F17	92
IO192PB5F17	93
Bank 6	
IO193PB6F18	86
IO194NB6F18	84
IO194PB6F18	85
IO196NB6F18	78
IO196PB6F18	79
IO197NB6F18	82
IO197PB6F18	83
IO198NB6F18	76
IO198PB6F18	77
IO203NB6F19	72
IO203PB6F19	73
IO204NB6F19	70
IO204PB6F19	71
IO205NB6F19	66
IO205PB6F19	67
IO206NB6F19	64
IO206PB6F19	65
IO207NB6F19	60
IO207PB6F19	61
IO208NB6F19	58
IO208PB6F19	59
IO211NB6F19	54
IO211PB6F19	55
IO212NB6F19	52
IO212PB6F19	53
IO223NB6F20	48
IO223PB6F20	49

CQ352	
AX1000 Function	Pin Number
IO224NB6F20	46
IO224PB6F20	47
Bank 7	
IO225NB7F21	40
IO225PB7F21	41
IO226NB7F21	42
IO226PB7F21	43
IO237NB7F22	34
IO237PB7F22	35
IO238NB7F22	36
IO238PB7F22	37
IO240NB7F22	30
IO240PB7F22	31
IO241NB7F22	28
IO241PB7F22	29
IO242NB7F22	24
IO242PB7F22	25
IO244NB7F22	22
IO244PB7F22	23
IO245NB7F22	18
IO245PB7F22	19
IO246NB7F22	16
IO246PB7F22	17
IO249NB7F23	12
IO249PB7F23	13
IO250NB7F23	10
IO250PB7F23	11
IO256NB7F23	4
IO256PB7F23	5
IO257NB7F23	6
IO257PB7F23	7
Dedicated I/O	
GND	1
GND	9
GND	15

Revision	Changes	Page
Revision 8 (continued)	The following changes were made in the "FG676"(AX500) section: AE2, AE25 Change from NC to GND. AF2, AF25 Changed from GND to NC AB4, AF24, C1, C26 Changed from V_{CCDA} to V_{CCA} AD15 Change from V_{CCDA} to V_{COMPLE} AD17 Changed from V_{COMPLE} to V_{CCDA}	3-37
	In the "FG896" (AX2000) section, the AK28 changed from VCCIB5 to VCCIB4.	3-52
	The "CQ352" and "CG624" sections are new.	3-98, 3-115
Revision 7 (Advance v1.6)	All I/O FIFO capability was removed.	n/a
	Table 1 was updated.	i
	Figure 1-9 was updated.	1-7
	Figure 2-5 was updated.	2-16
	The "Using an I/O Register" section was updated.	2-16
	The AX250 and AX1000 descriptions were added to the "FG484"section.	3-21
Revision 6 (Advance v1.5)	Table 2-3 was updated.	2-2
	Figure 2-1 was updated.	2-8
	Figure 2-48 was updated.	2-75
	Figure 2-52 was updated.	2-82
Revision 5 (Advance v1.4)	In the "PQ208" table, pin 196 was missing, but it has been added in this version with a function of GND.	3-84
	The following pins in the "FG484" table for AX500 were changed: Pin G7 is GND/LP Pins AB8, C10, C11, C14, AB16 are NC.	3-21
	The "FG676" table was updated.	3-37
Revision 4 (Advance v1.3)	The "Device Resources" section was updated for the CS180.	ii
	The "Programmable Interconnect Element" and Figure 1-2 are new.	1-1 and 1-2
	The "CS180" table is new.	3-1
	The "PQ208" tables for the AX500 were updated. The following pins were not defined in the previous version: GND 21 IO106PB5F10/CLKHP 71 GND 136	3-84
Revision 3 (Advance v1.2)	Table 1, "Ordering Information", "Device Resources", and the Product Plan table were updated.	i, ii
	The following figures and tables were updated: Figure 1-3 Figure 1-8 (new) Table 2-3 Figure 2-2 Table 2-8 Figure 2-11	 1-2 1-6 2-2 2-9 2-12 2-23
	The "Design Environment" section was updated.	1-7
	The "Package Thermal Characteristics" was updated.	2-6